

Description

The 2N7002 uses advanced technology to provide excellent RDS(ON), low gate charge and low gate voltages during operation. This device is suitable for use as a load switch or in PWM applications.

General Features

• $V_{DS} = 60V$, $I_{D} = 500mA$

 $R_{DS(ON)}$ < 3 Ω @V_{GS}= 10V

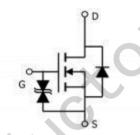
 $R_{DS(ON)}$ < 4 Ω @V_{GS}=4.5V

- · High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package
- ESD Rating:>2000V HBM

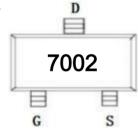
Application

- PWM applications
- Load switch
- Power management





Schematic diagram



Marking and pin assignment

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	VDS	60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	0.5	А
Pulsed Drain Current(Note 1)	Ірм	1.2	А
Maximum Power Dissipation	Po	0.35	W
Operating Junction and Storage Temperature Range	TJ,TsTG	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient(Note 2)	Reja	357	°CM
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2N7002带ESD版本 N-Channel Enhancement Mode Power MOSFET

Electrical Characteristics (TA=25℃ unless otherwise noted)

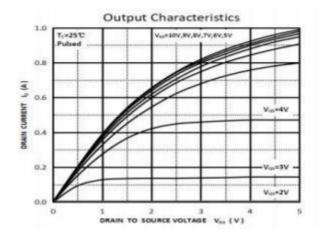
Parameter	Symbol Condition		Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	Vgs=0V,ID=250µA	60	_	_	V
Zero Gate Voltage Drain Current	IDSS	V _{DS} =48V,V _{GS} =0V	_	_	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	_	_	±10	μA
On Characteristics(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	VDS=VGS,ID= 1mA	8.0	1.5	2.5	V
		Vgs= 10V,lp=0.5A	_	1.9	3	Ω
Drain-Source On-State Resistance	RDS(ON)	Vgs=4.5V,lp=0.2A	_	2.4	4	Ω
Dynamic Characteristics(Note 4)						
Input Capacitance	Ciss		-	4	40	pF
Output Capacitance	Coss	V _{DS} = 10V,V _{GS} =0V, F=1.0MHz	-		30	pF
Reverse Transfer Capacitance	Crss	1 – 1.0IVII 12		_	10	pF
Switching Characteristics(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =50V,R _G =50Ω,	-	-	10	nS
Tum-Off Delay Time	t _{d(off)}	V _{GS} = 10V,R _{GS} =50Ω R _L =250Ω	-	-	15	nS
Reverse Charge Capacity	Qr	Is=0.3A,V _R =25V,	_	30	_	nC
Reverse Recovery Time	trr	Vgs=0V, dIs/dt=-100A/uS	_	30	_	nS
Drain-Source Diode Characteristics						
Diode Forward Voltage(Note 3)	V _{SD}	Vgs=0V,ls=0.3A	_	_	1.5	V
Gate Source Zener Breakdown Voltage	BVGSO	Igs=±1mA (Open Drain)	±21.5	_	±30	V

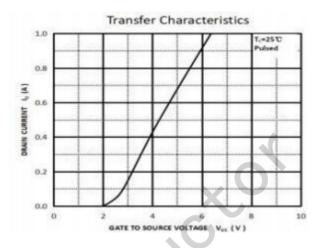
Notes:

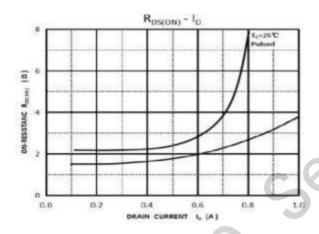
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width ≤ 300 µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to product.

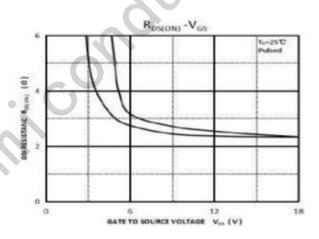


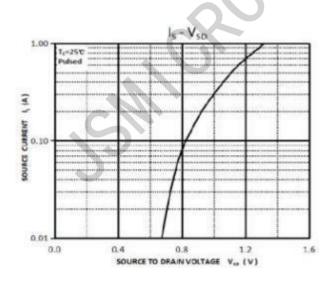
Typical Electrical and Thermal Characteristics







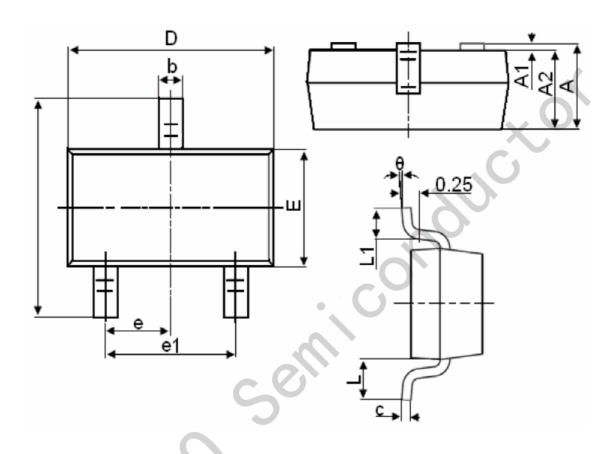






Package Information

SOT-23



Cyma b al	Dimensions in Millimeters(mm)		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950TYP		0.037TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550REF		0.022REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	